

BergStak® 0.8mm Mezzanine Connector

Extraordinary product range, Benchmark performance, Dual-source champion

FLEXIBLE SOLUTION FOR HIGH DENSITY APPLICATIONS

Amphenol's BergStak® 0.8 mm is a flexible solution designed for high-speed and high-density, parallel board-to-board connector systems with 16 PCB stack heights in 10 sizes up to 200 positions.

- Housing and terminal profile guarantees support of up to 12 Gb/s
- Vertical versus vertical mating configuration
- 20 to 200 position sizes in 20 position increments
- 5 mm to 20 mm stack heights in 1mm increments



TARGET MARKETS



FEATURES

- Housing and terminal profile guarantees support of up to 12 Gb/s
- Vertical versus vertical mating configuration
- 20 to 200 position sizes in 20 position increments
- 5mm to 20mm stack heights in 1mm increments
- 0.8mm double-row contact pitch conserves printed circuit board space
- Scoop-proof feature housings
- Multiple plating options available
- Multiple packaging options available
- PCB locator pegs option
- Available in UL94-V0 material
- RoHS compliant and lead-free

BENEFITS

- Compatible with PCIe Gen 2/3 and SAS 3.0 high speed performance on selected stack heights
- Suitable for parallel board stacking applications
- Comprehensive range of sizes and stack heights to satisfy all needs
- High density for all electrical applications needs
- Prevents reverse mating
- Satisfies different application requirement
- Suitable for varies feeding processing
- Facilitates ease and accuracy during manual assembly
- High flammability rating
- Meets environmental, health, and safety requirements

TECHNICAL INFORMATION

MATERIAL

- Housing: Glass filled LCP, UL94V-0
- Contact Base Metal
- Receptacle: Copper Alloy, High Spring
- Plug: Brass
- Contact Area Finish: Gold or Gold flash over Palladium-nickel (GXT®) over Nickel
- Solder Area Finish: Matte pure Tin over Nickel

MECHANICAL PERFORMANCE

- Durability: 100 mating cycles
- Mating Force: 0.9 N max./contact
- Unmating Force: 0.1 N min./contact

ELECTRICAL PERFORMANCE

- Insulation Resistance:
 - Initial: 1000 MΩ min.
 - After Test: 100 MΩ min.
- Current Rating: 0.8A/contact
- Contact Resistance:
 - Initial: 30 mΩ max.
 - After Test: 50 mΩ max.
- Voltage Rating: 100 VAC
- Signal Integrity (Differential pairs, connector and SMT pads only)
 - Impedance Range: 81 to 108Ω @ 50 ps edge (10–90%)
 - Return Loss: < 10 dB up to 5 GHz
 - Insertion Loss: < 1.5 dB up to 5 GHz
 - NEXT: ≤ 4.0% for a 50 ps edge (10–90%)
 - FEXT: ≤ 2.4% for a 50 ps edge (10–90%)

ENVIRONMENTAL

- Temperature Range: –40 °C to +125 °C
- High Temperature Life: 105 °C ± 5 °C for 1000 hours
- Humidity: 90–95% relative humidity for 96 hours
- Mixed Flowing Gas Class 2a (30 GXT®)

APPROVALS AND CERTIFICATIONS

- UL E66906
- File no. LR46923

SPECIFICATIONS

- Product Specification: GS-12-547
- Test Report: DGS-29-010

PACKAGING

- Tape & Reel
- Tubes

TARGET MARKETS/APPLICATIONS



IP Phone
Router



Server

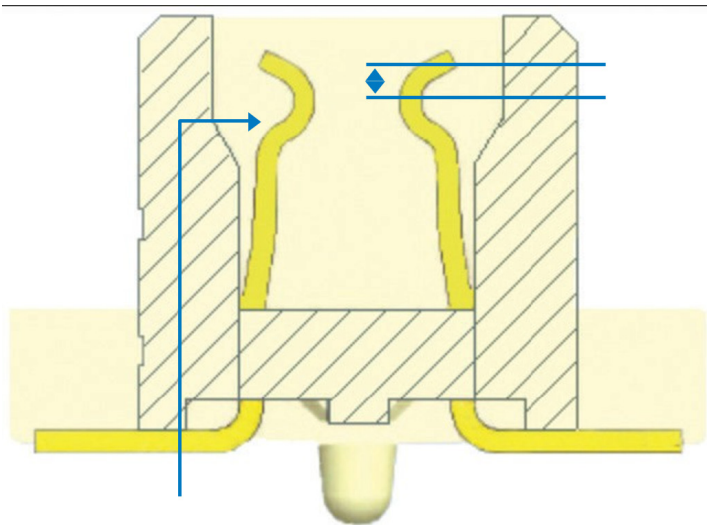


Industrial and Instrumentation
Office Equipment
Point-Of-Sale Terminal
Portable Industrial Terminal
Test and Measurement



Diagnostics Systems

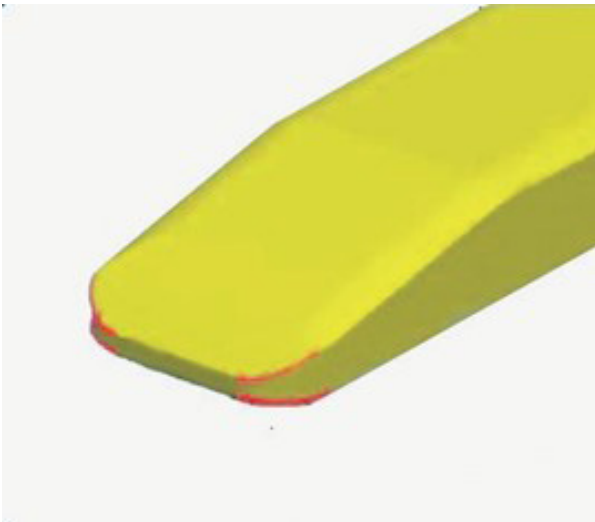
RECEPTACLE



Early-contact point allows early engagement/ late disengagement and increases mating wipe

Precision-tapered contacts control mating stress while providing reliable, high normal force

HEADER



Early-contact point allows early engagement/ late disengagement and increases mating wipe

Coined contact tips assure smooth, safe wiping action during connector mating

PART NUMBER SELECTOR

Find part number details using the search box on www.amphenol-cs.com

XXXXX

XX

HOUSING HEIGHT

X

X

X

LF

Lead-free

Base Part Number

Receptacle	61082
Plug	61083

Total Positions

20 pos	02
40 pos	04
60 pos	06
80 pos	08
100 pos	10
120 pos	12
140 pos	14
160 pos	16
180 pos	18
200 pos	20

Packaging Option

Tube without metal cap	0
Tape & Reel with metal caps	2
Tape & Reel without metal cap (with Kapton tape)	6
Tube with metal caps	9

Peg Option

Includes polarization pegs	0
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Plating Code

Gold 0.2 µm min./Pure Tin 2 µm min. (Lead-free) Nickel underplate overall 1.27 µm min.	4
Gold 0.38 µm min./Pure Tin 2 µm min. (Lead-free) Nickel underplate overall 1.27 µm min.	5
Gold Flash (0.1 µm min.) over Palladium-Nickel 0.76 µm min./Pure Tin 2 µm (Lead-free) Nickel underplate overall 1.27 µm min.	6

X	FOR PLUG, SEE DWG. NO. 61083			
COMBINATION OF MATED HEIGHT	Plug 1	Plug 2	Plug 3	Plug 4
Recep 1				
Recep 2				
Recep 3				
Recep 4				

WHERE INNOVATION CONNECTS

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